



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Stanford W. CRANE, Jr. et al.

Application No.: 09/964,542

Filed: September 28, 2001

For: PREFABRICATED SEMICONDUCTOR
CHIP CARRIER

Commissioner for Patents
Washington, D.C. 20231

Sir:

Group Art Unit: 2827

Examiner: J. Norri

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RESPONSE

In response to the Office action of April 24, 2002, Applicant respectfully requests reconsideration of the subject application in view of the following amendments and remarks. The period for response to this Office Action has been extended through August 26, 2002, by a petition for a one-month extension of time filed concurrently herewith.

In the claims:

Please cancel claim 1 and add the following new claims 47-55:

47. (New) A semiconductor die carrier comprising:
- a housing for holding at least one semiconductor die and including:
 - an end surface having a perimeter; and
 - a peripheral side wall connected to the end surface, extending about the perimeter of the end surface and including an outer peripheral surface and an inner peripheral surface;
 - an inner wall within the perimeter of the end surface and including an outer surface spaced from and opposing the inner peripheral surface of the peripheral side wall, and an inner surface facing the center of the housing; and